

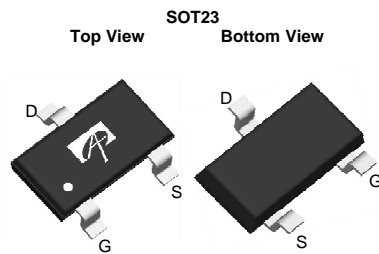
General Description

The GX3415A uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch applications.

Product Summary

V_{DS}	-20V
I_D (at $V_{GS}=-4.5V$)	-5A
$R_{DS(ON)}$ (at $V_{GS}= -4.5V$)	< 41m Ω
$R_{DS(ON)}$ (at $V_{GS}= -2.5V$)	< 53m Ω
$R_{DS(ON)}$ (at $V_{GS}= -1.8V$)	< 65m Ω

ESD protected



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$	-5
		$T_A=70^\circ\text{C}$	-4
Pulsed Drain Current ^C	I_{DM}	-30	A
Power Dissipation ^B	P_D	$T_A=25^\circ\text{C}$	1.5
		$T_A=70^\circ\text{C}$	1
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	65	80	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Ambient ^{A,D}		Steady-State	85	100
Maximum Junction-to-Lead	$R_{\theta JL}$	43	52	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-20			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-20\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-1 -5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 8\text{V}$			± 10	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-0.3	-0.57	-0.9	V
$I_{D(ON)}$	On state drain current	$V_{GS}=-4.5\text{V}, V_{DS}=-5\text{V}$	-30			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5\text{V}, I_D=-4\text{A}$ $T_J=125^\circ\text{C}$		34 49	41 59	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}, I_D=-4\text{A}$		42	53	$\text{m}\Omega$
		$V_{GS}=-1.8\text{V}, I_D=-2\text{A}$		52	65	$\text{m}\Omega$
		$V_{GS}=-1.5\text{V}, I_D=-1\text{A}$		61		$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-4\text{A}$		20		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.64	-1	V
I_S	Maximum Body-Diode Continuous Current				-2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-10\text{V}, f=1\text{MHz}$	600	751	905	pF
C_{oss}	Output Capacitance		80	115	150	pF
C_{rss}	Reverse Transfer Capacitance		48	80	115	pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	6	13	20	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=-4.5\text{V}, V_{DS}=-10\text{V}, I_D=-4\text{A}$	7.4	9.3	11	nC
Q_{gs}	Gate Source Charge		0.8	1	1.2	nC
Q_{gd}	Gate Drain Charge		1.3	2.2	3.1	nC
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=-4.5\text{V}, V_{DS}=-10\text{V}, R_L=2.5\Omega,$ $R_{GEN}=3\Omega$		13		ns
t_r	Turn-On Rise Time			9		ns
$t_{D(off)}$	Turn-Off DelayTime			19		ns
t_f	Turn-Off Fall Time			29		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-4\text{A}, dl/dt=500\text{A}/\mu\text{s}$	20	26	32	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-4\text{A}, dl/dt=500\text{A}/\mu\text{s}$	40	51	62	nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(MAX)}=150^\circ\text{C}$, using $\leq 10\text{s}$ junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$.

D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using $<300\mu\text{s}$ pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of $T_{J(MAX)}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

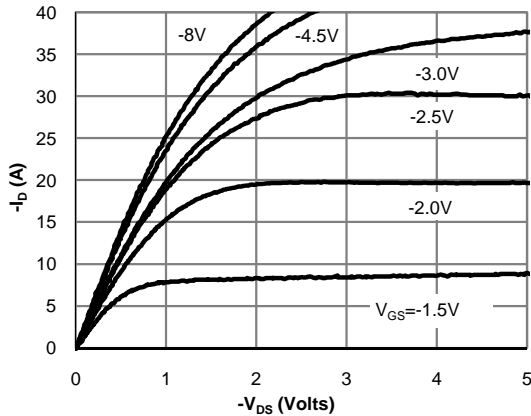


Fig 1: On-Region Characteristics (Note E)

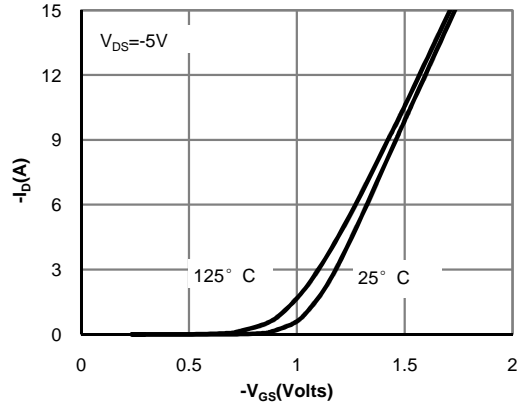


Figure 2: Transfer Characteristics (Note E)

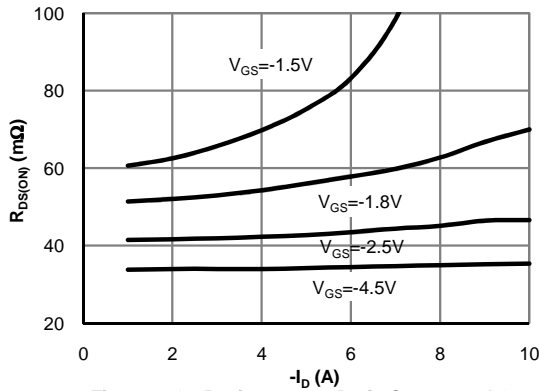


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

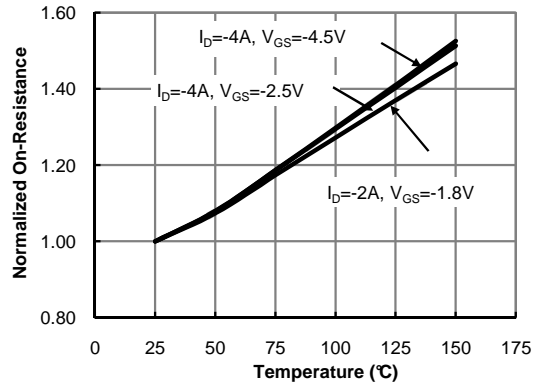


Figure 4: On-Resistance vs. Junction Temperature (Note E)

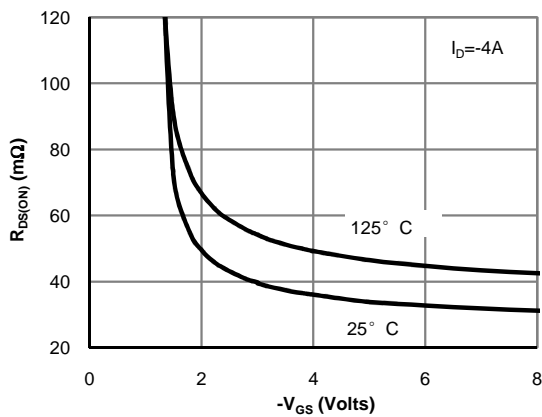


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

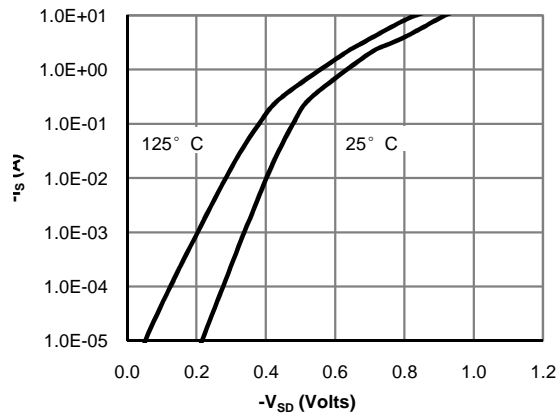


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

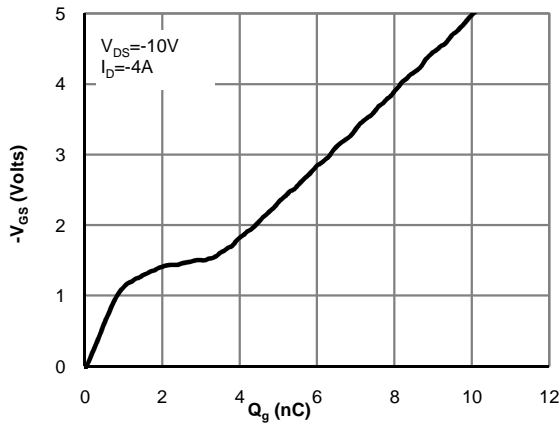


Figure 7: Gate-Charge Characteristics

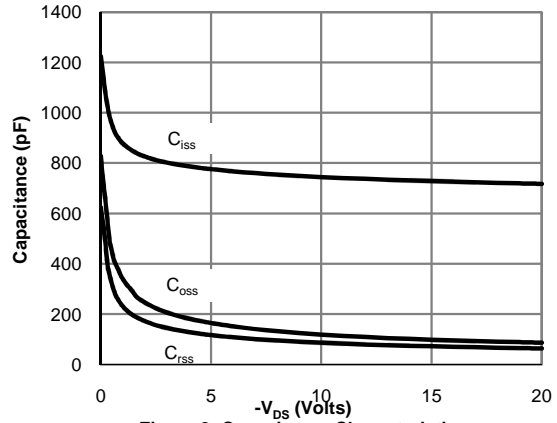


Figure 8: Capacitance Characteristics

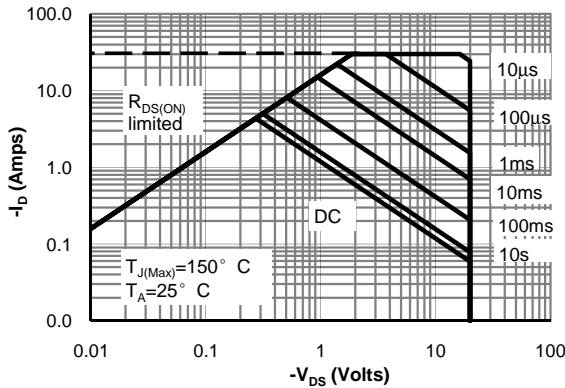


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

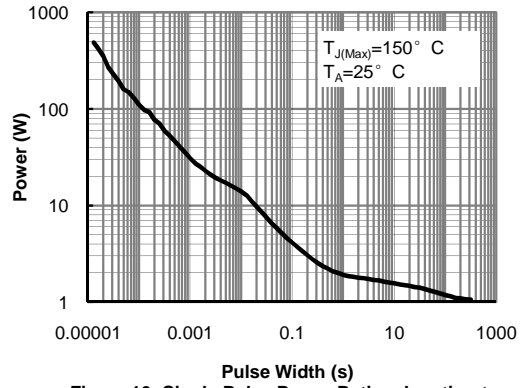


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

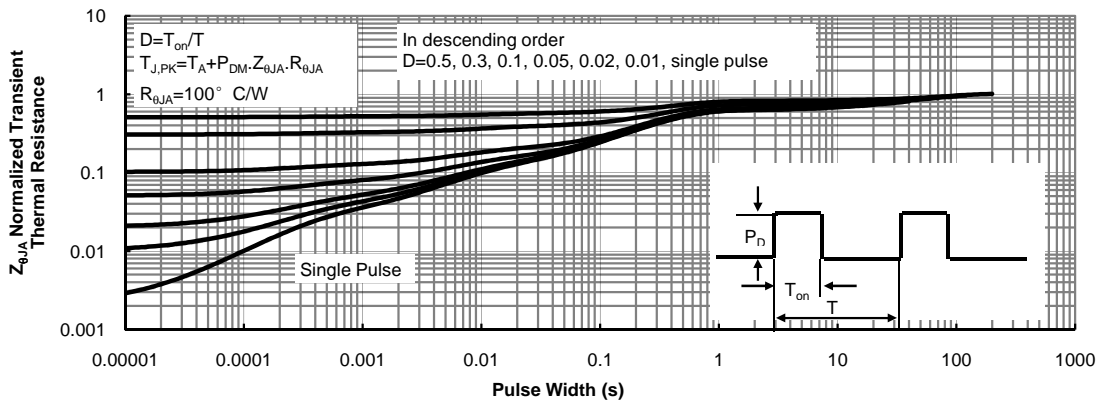
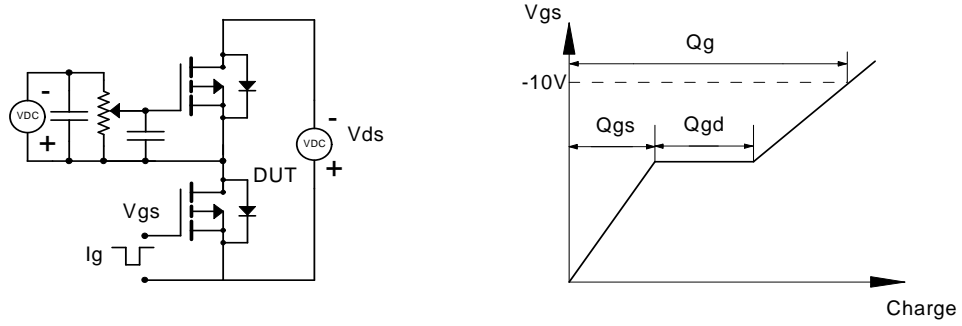
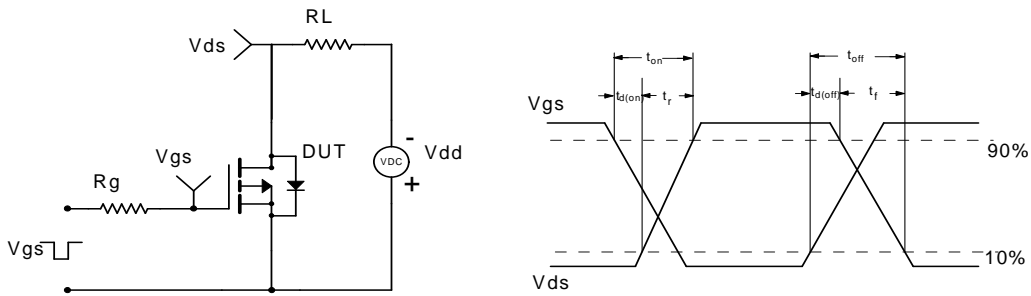


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

